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Dr. Lee is a principle engineer and head of Advanced Package Lab at Samsung Semiconductor R&D Center. He has led development of advanced package architectures for heterogeneous integration and next-generation technologies. He joined the Samsung's package development department in 2010. And he participated in the development of advanced package technologies such as FOWLP/PLP, TSV, HBM, and 2.5D PKG. He received Ph. D. of Material Science and Engineering from Korea Advanced Institute of Science and Technology (KAIST) in 2010.